

FIG. 1

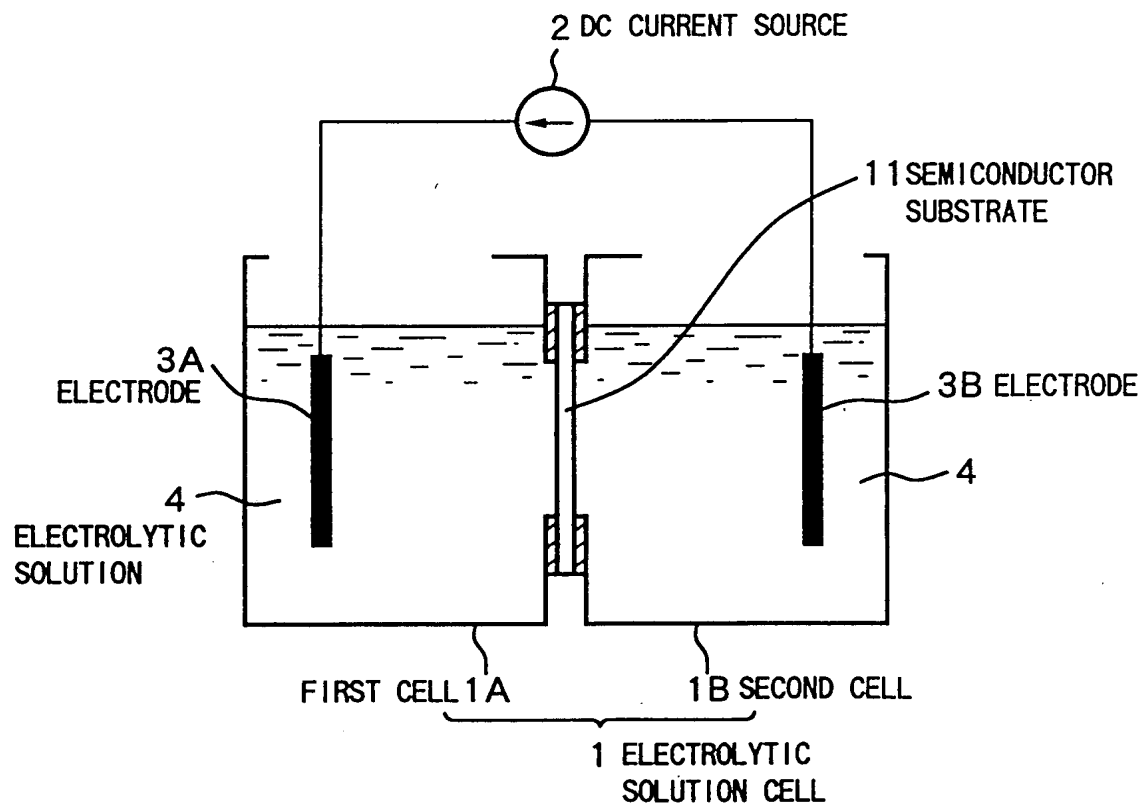


FIG.2A

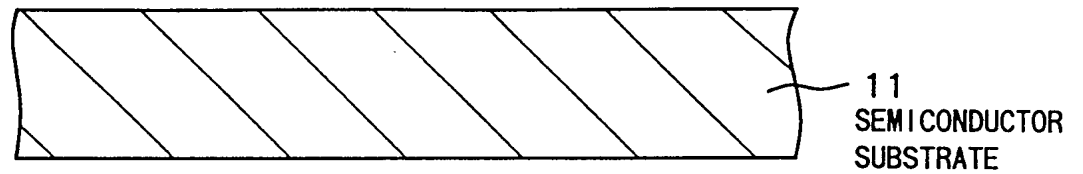


FIG.2B

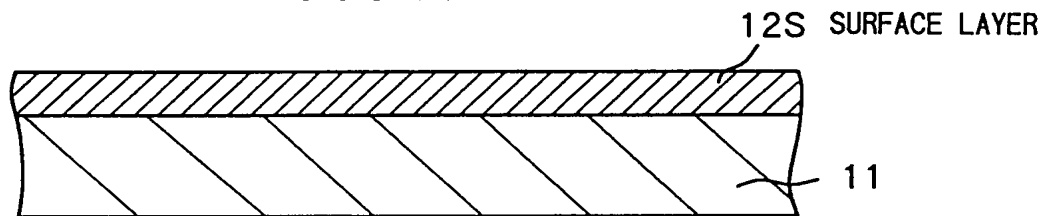
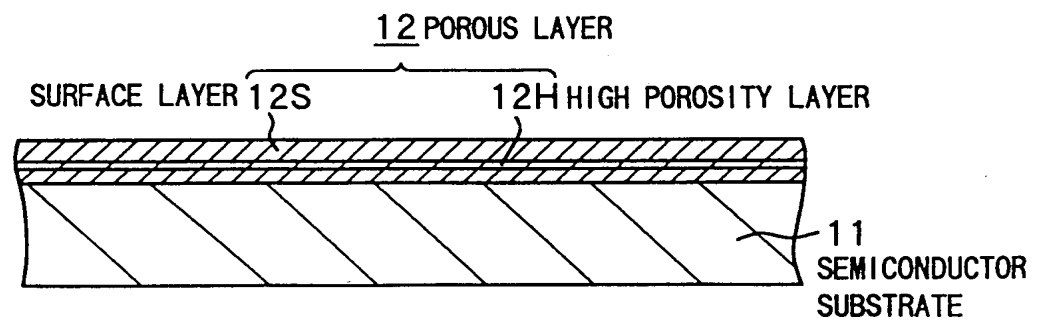
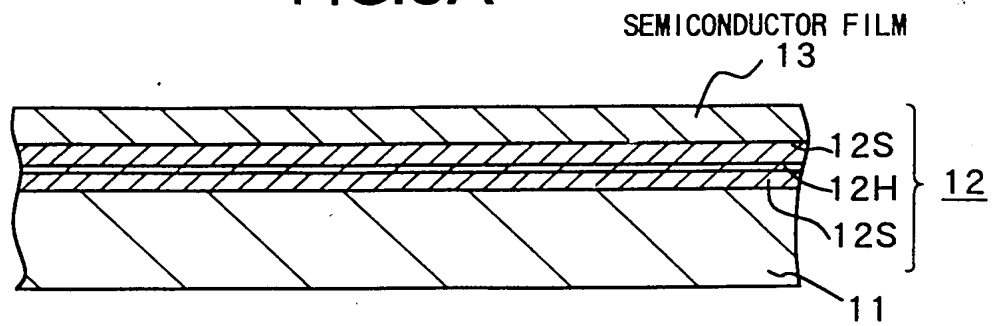


FIG.2C

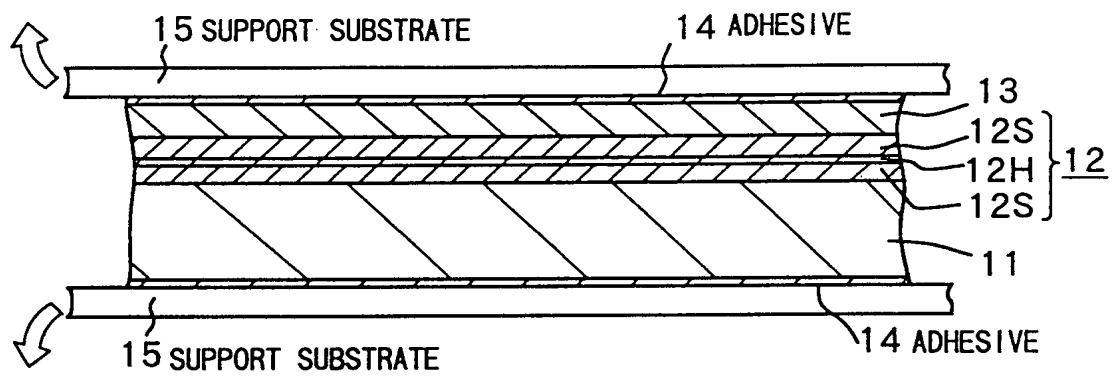


PROCESS DIAGRAM(FIRST)

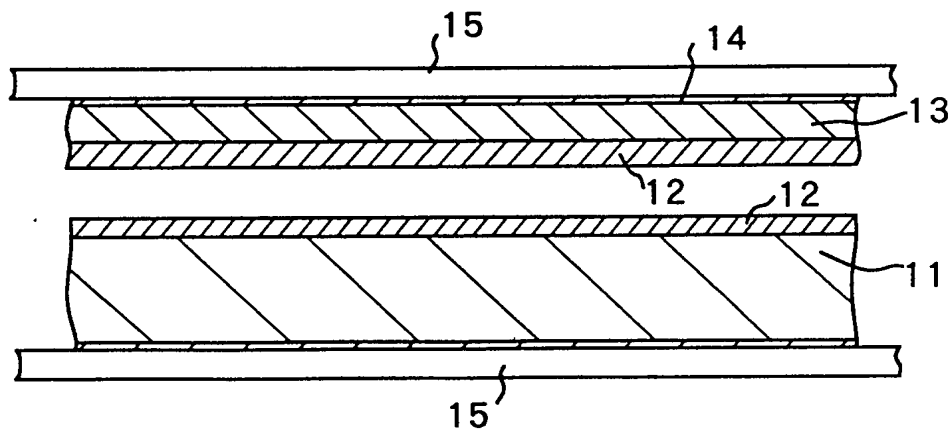
# FIG.3A



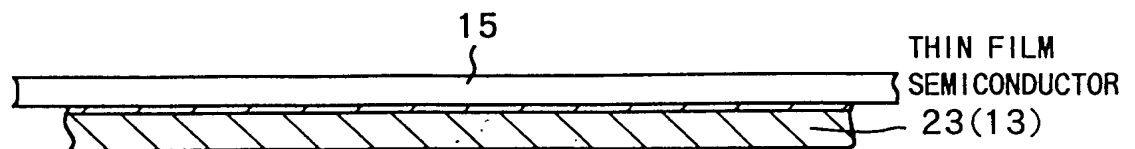
# FIG.3B



# FIG.3C



# FIG.3D



PROCESS DIAGRAM (SECOND)

FIG.4A

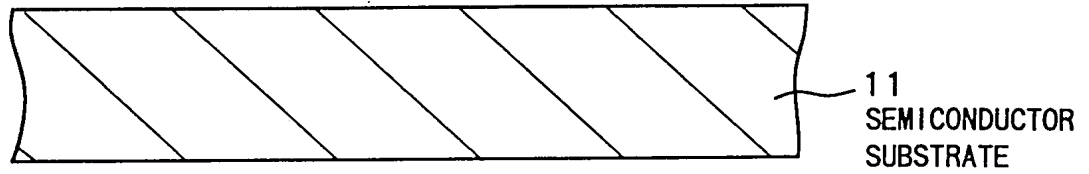


FIG.4B

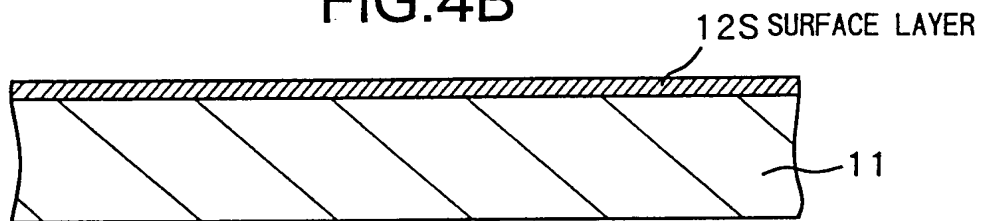


FIG.4C

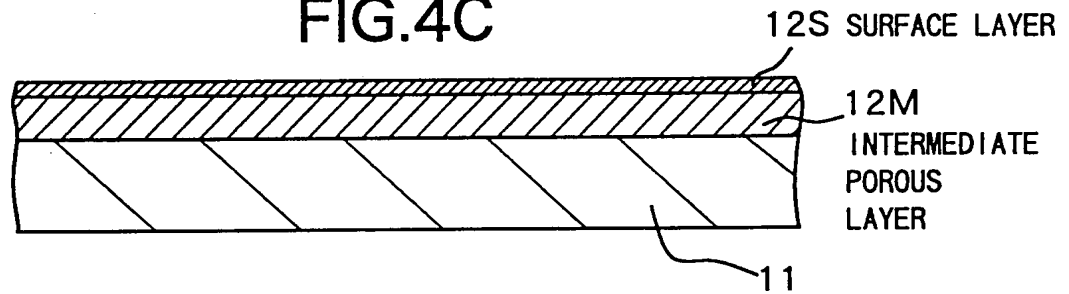
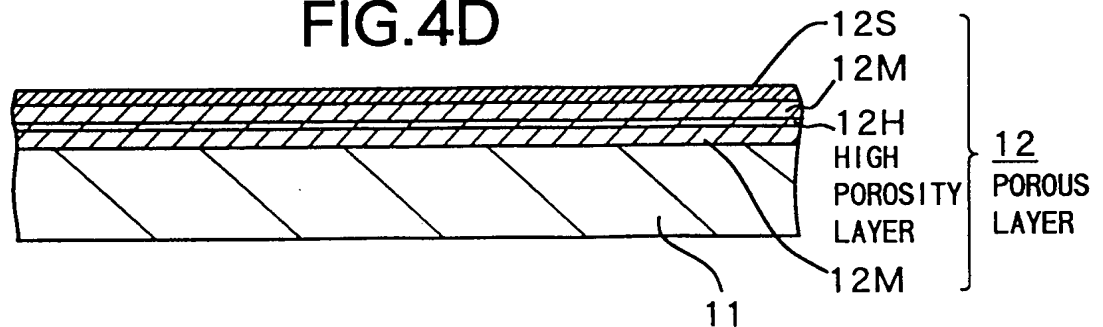


FIG.4D



PROCESS DIAGRAM(FIRST)

FIG.5A

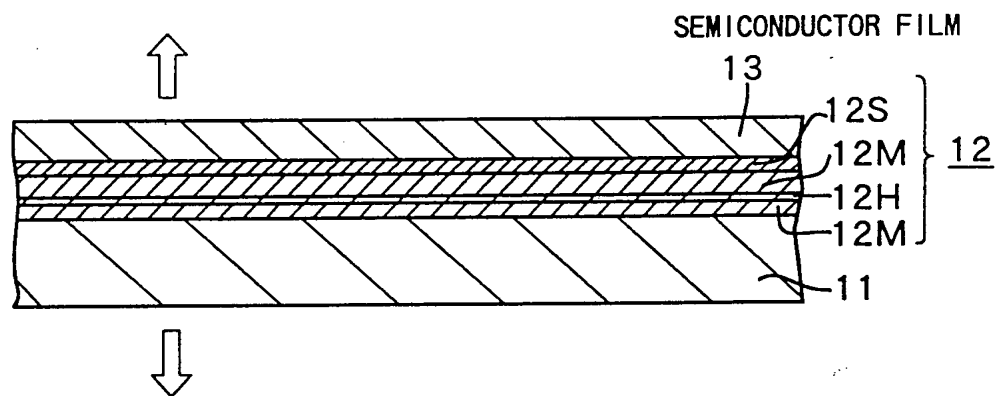
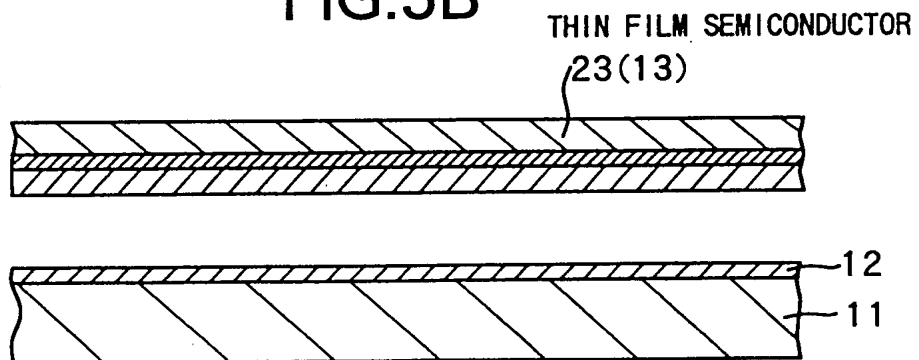


FIG.5B



PROCESS DIAGRAM (SECOND)

FIG.6A

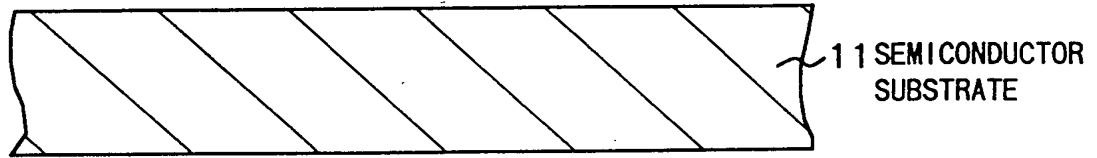


FIG.6B

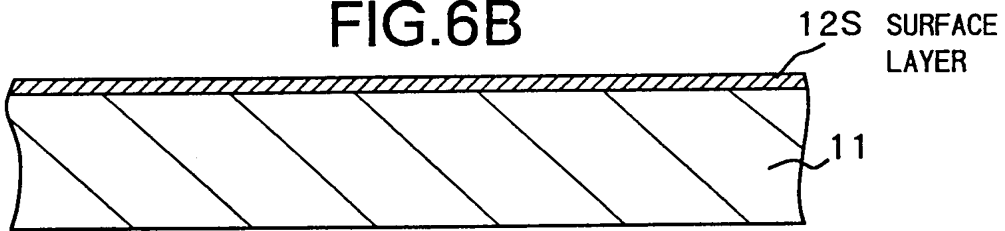


FIG.6C

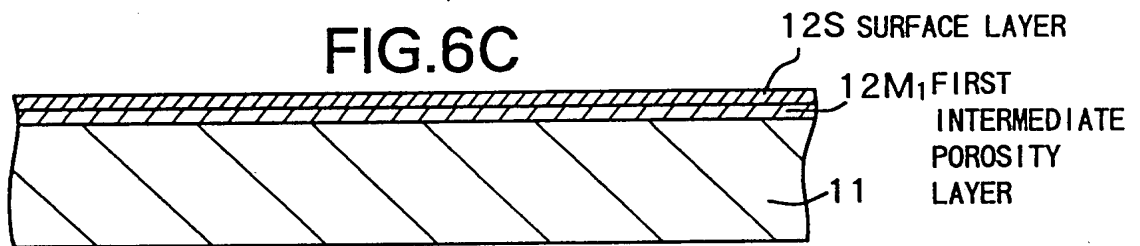


FIG.6D

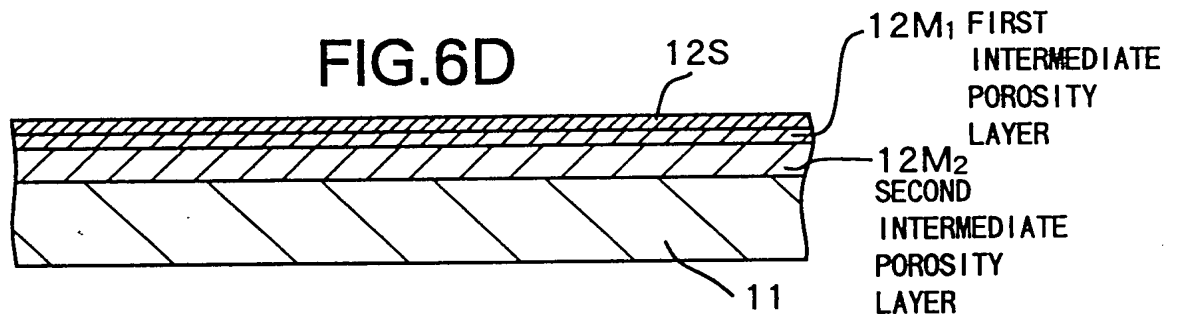
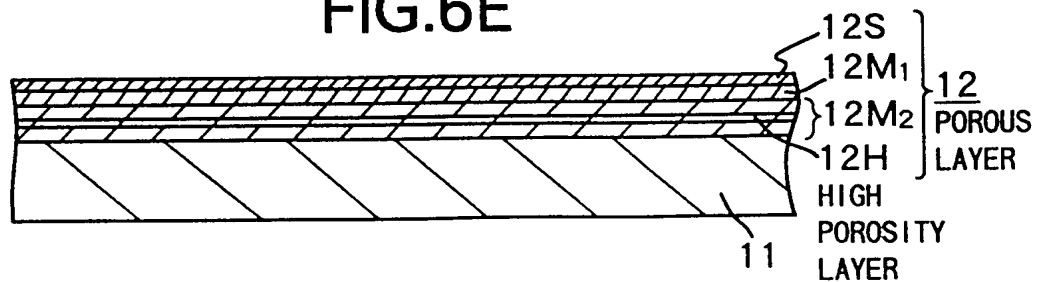
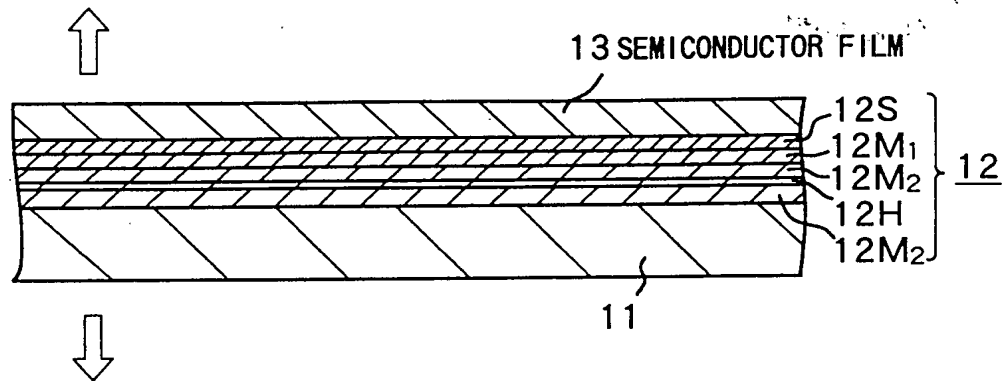


FIG.6E

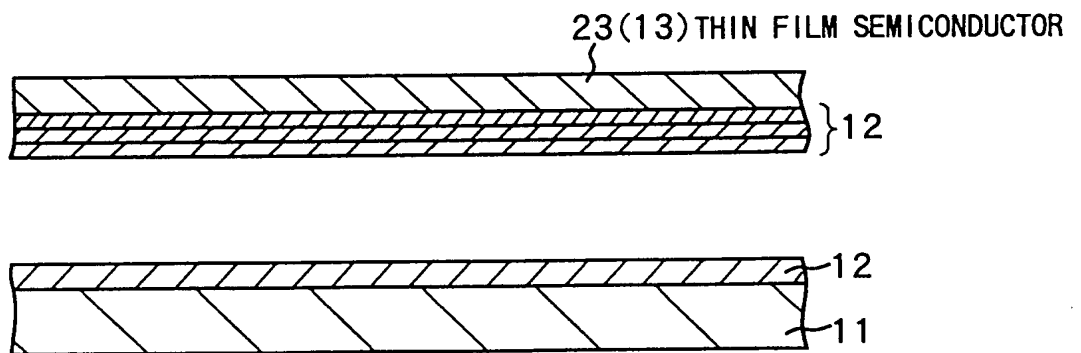


PROCESS DIAGRAM (FIRST)

# FIG.7A



# FIG.7B



PROCESS DIAGRAM (SECOND)

FIG.8A

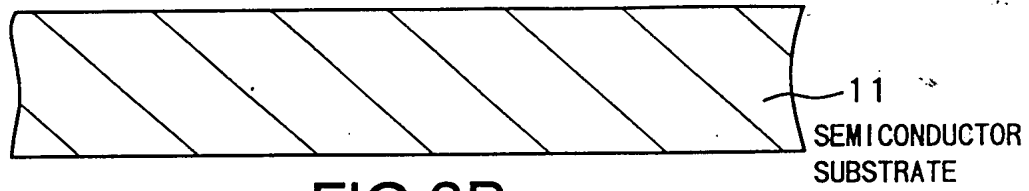


FIG.8B

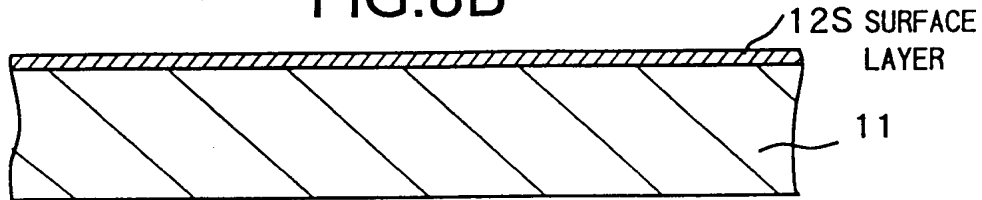


FIG.8C

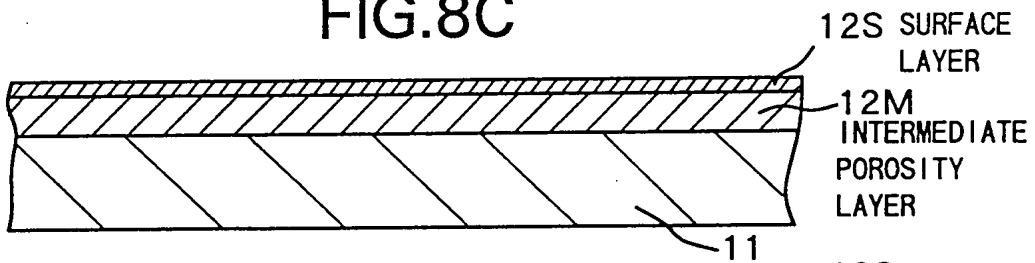


FIG.8D

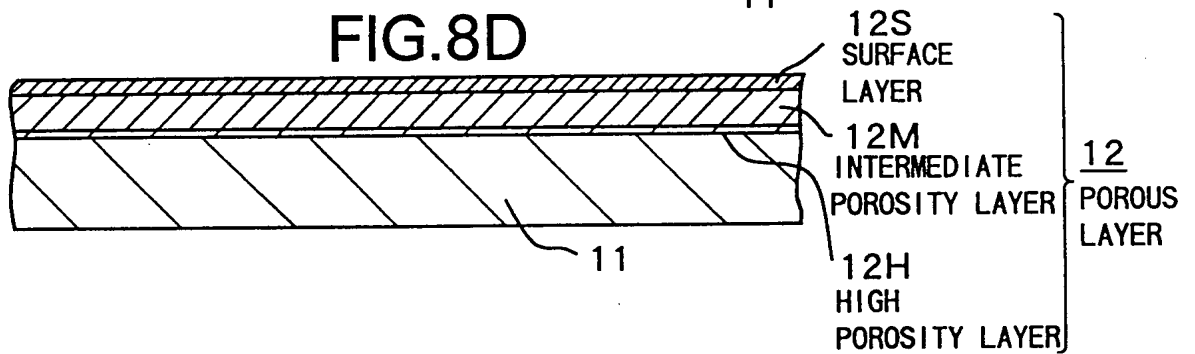


FIG.8E

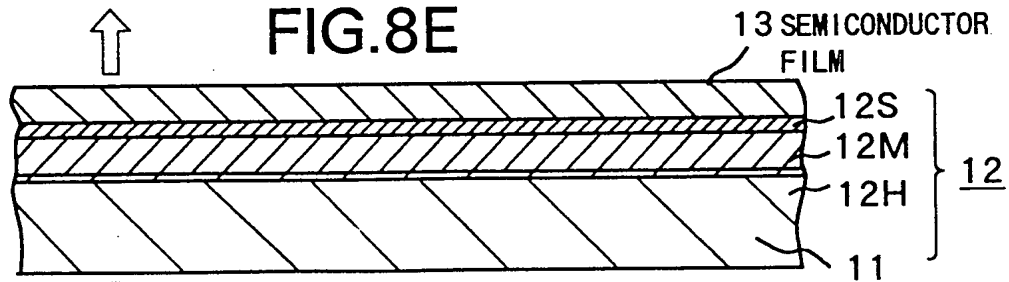
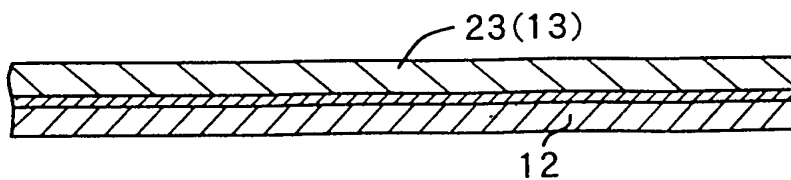


FIG.8F



PROCESS DIAGRAM



FIG.9A

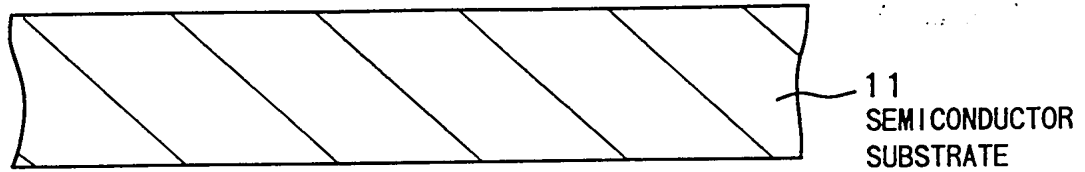


FIG.9B

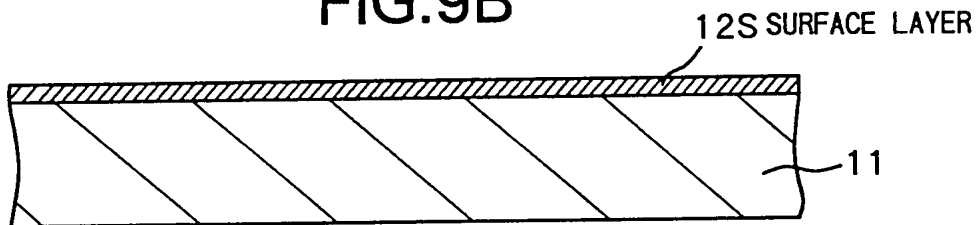


FIG.9C

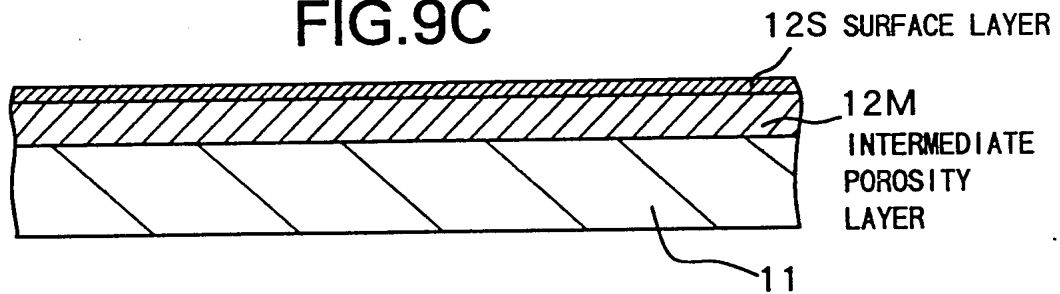
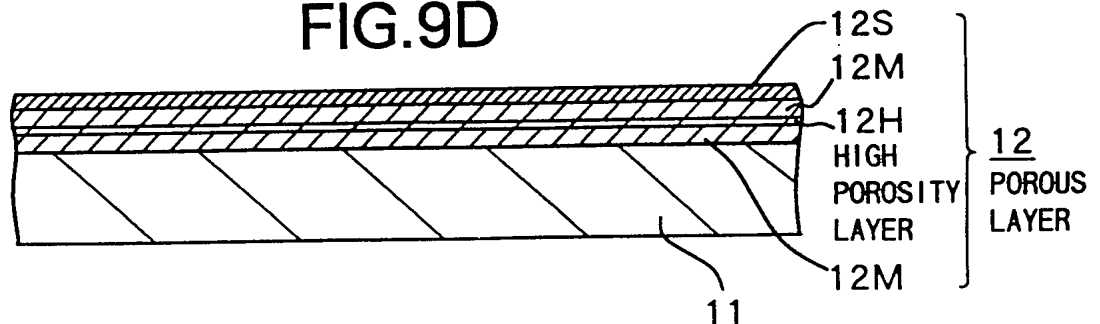
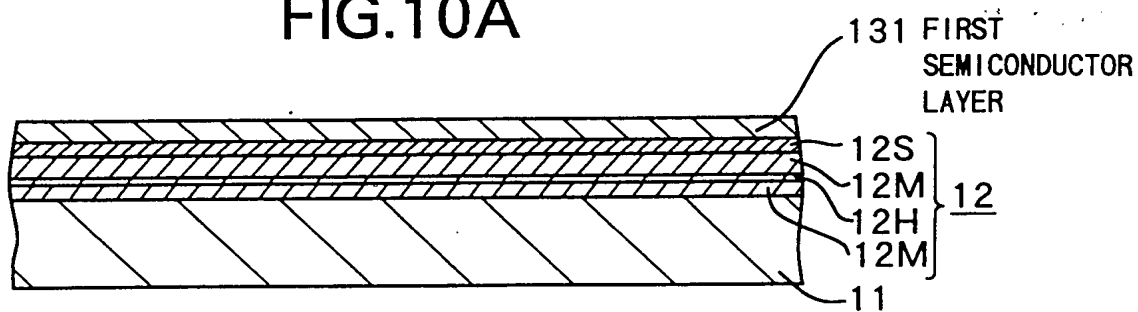


FIG.9D

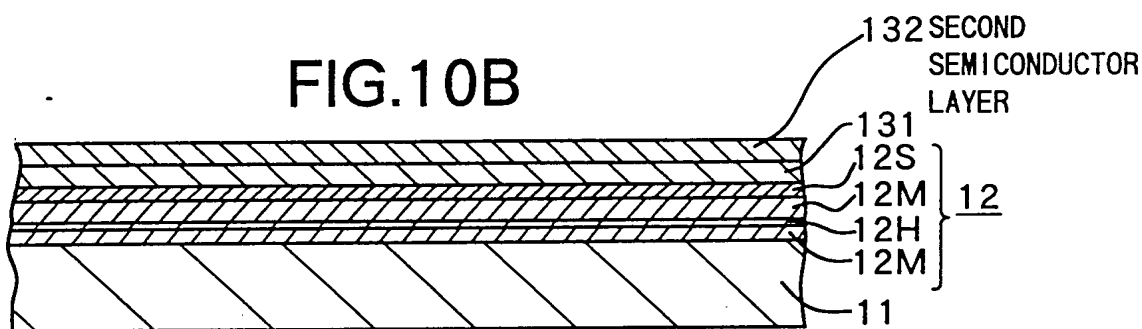


PROCESS DIAGRAM(FIRST)

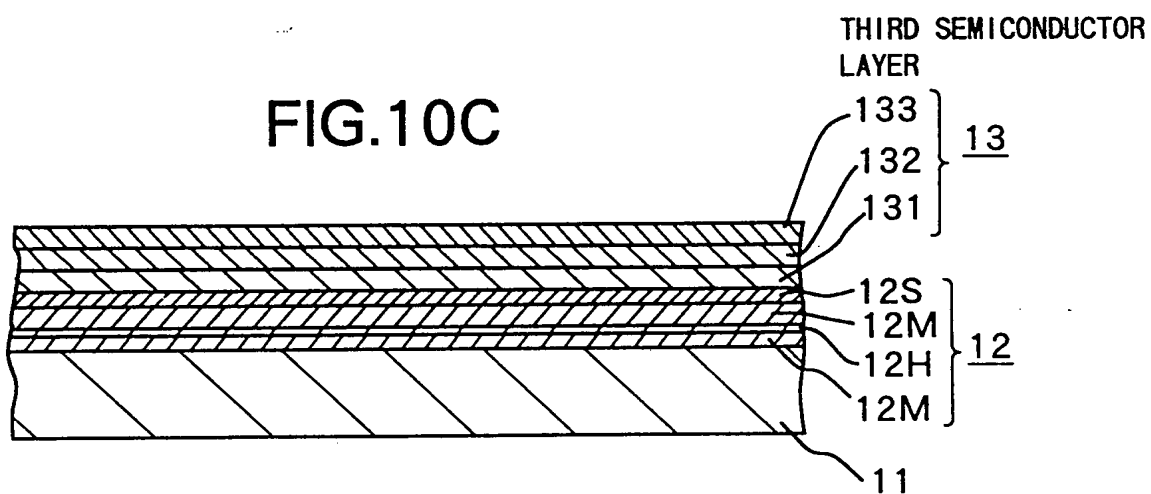
# FIG.10A



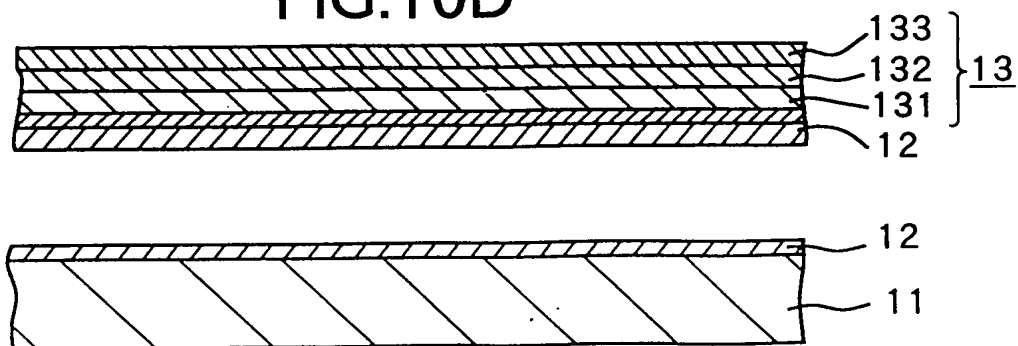
# FIG.10B



# FIG.10C



# FIG.10D



PROCESS DIAGRAM(SECOND)

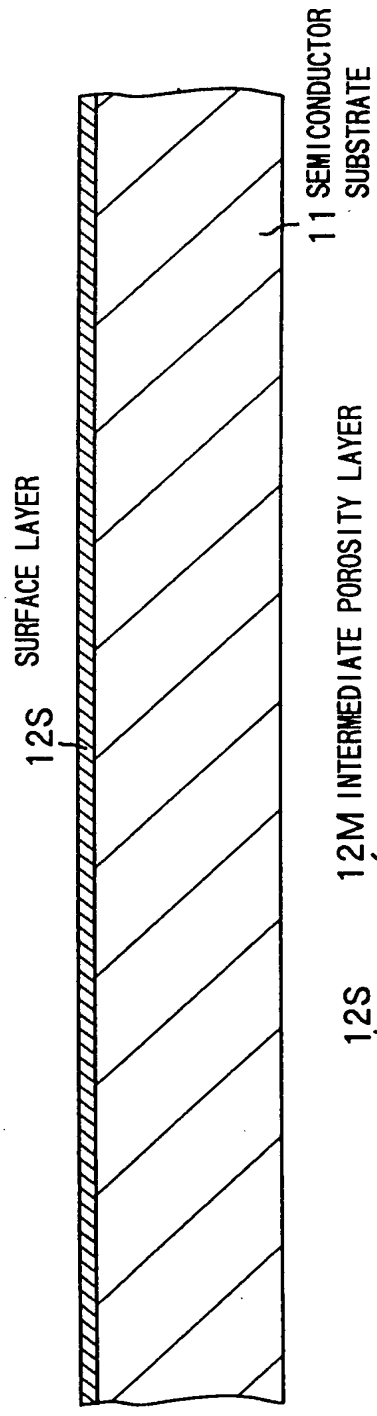


FIG.11A

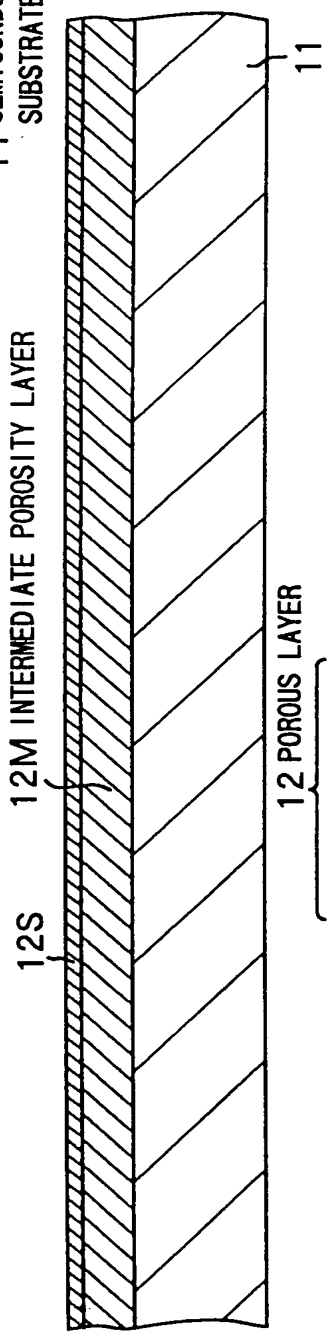


FIG.11B

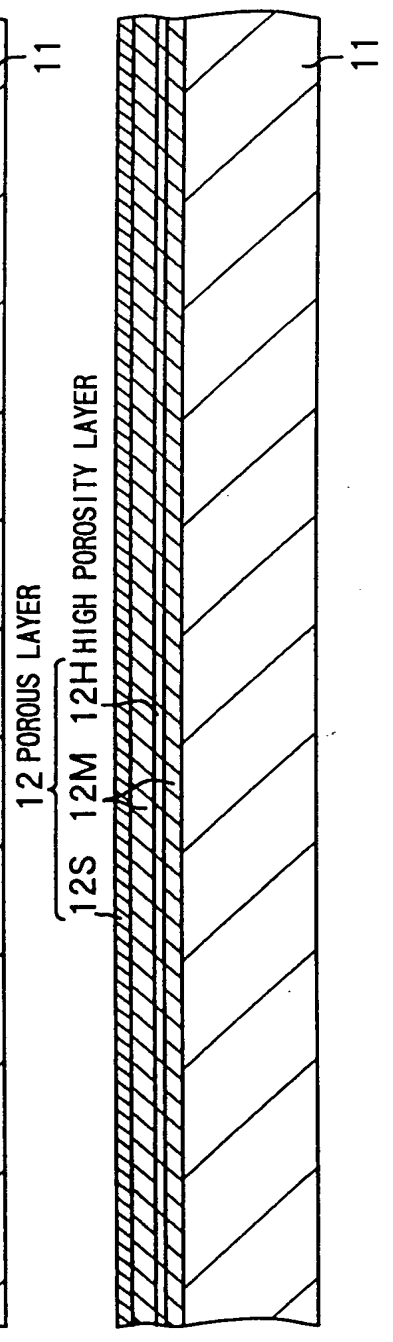


FIG.11C

PROCESS DIAGRAM(FIRST)

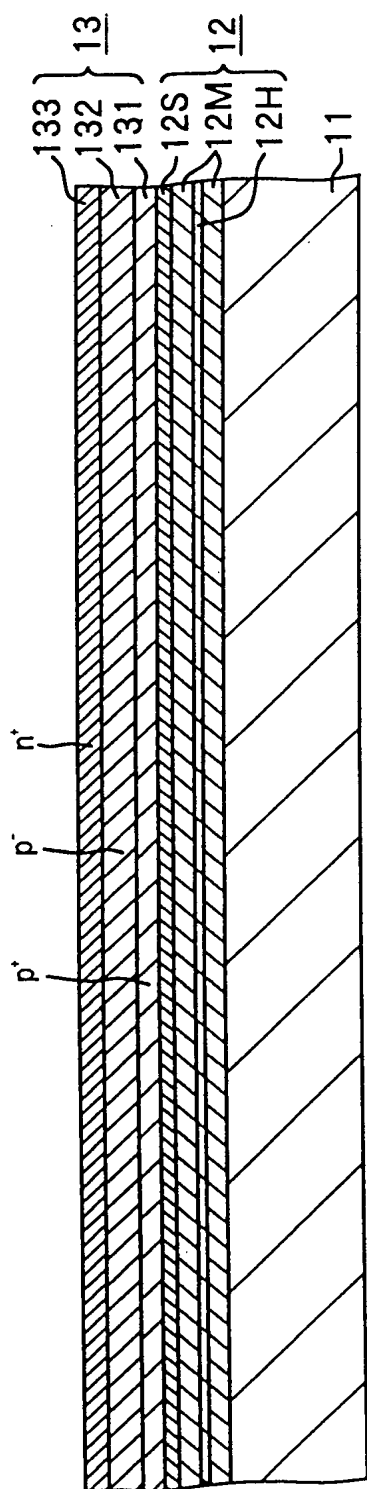


FIG.12A

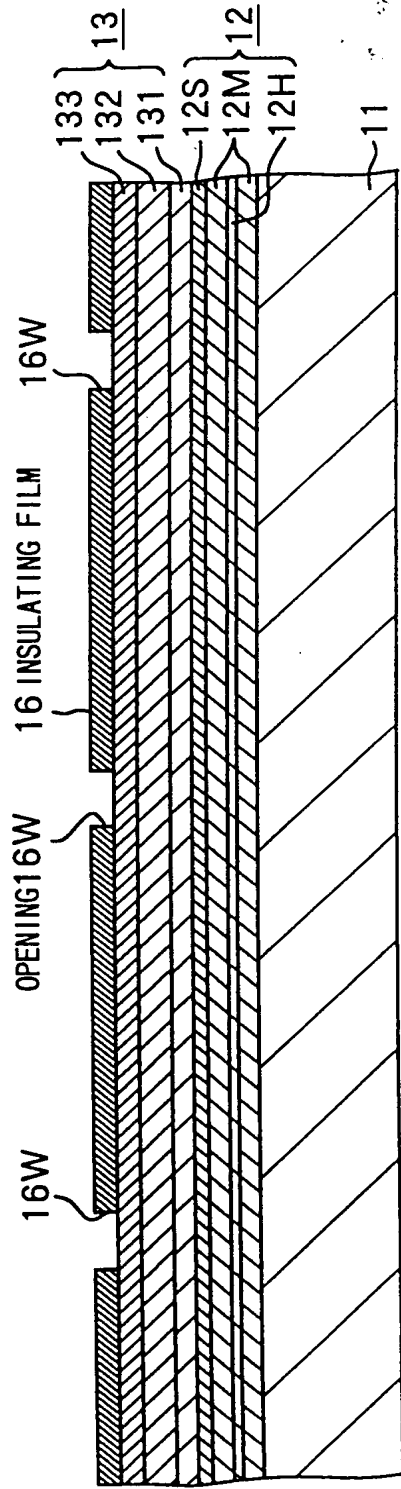


FIG.12B

PROCESS DIAGRAM (SECOND)

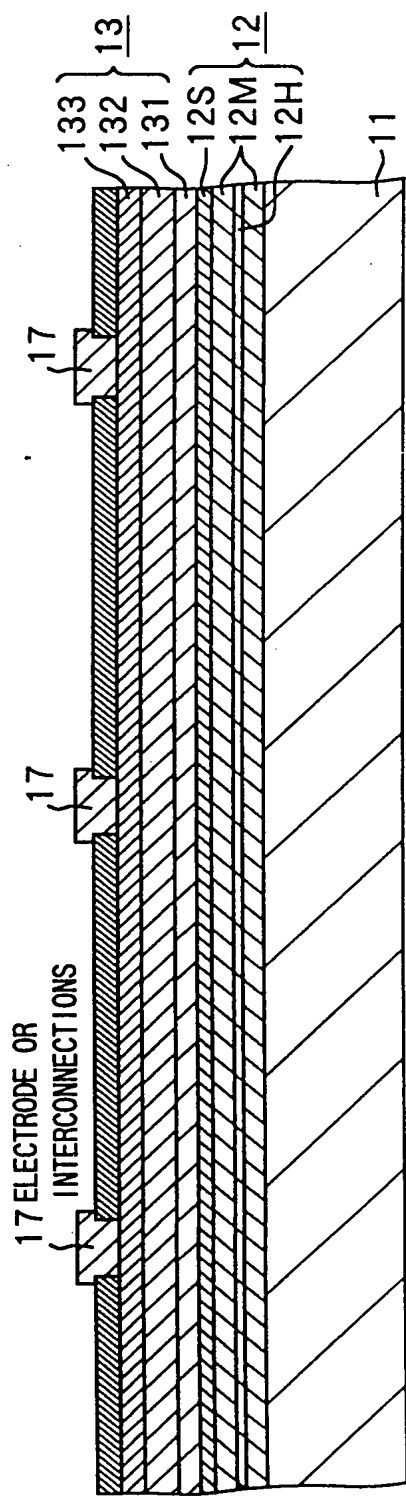


FIG.13A

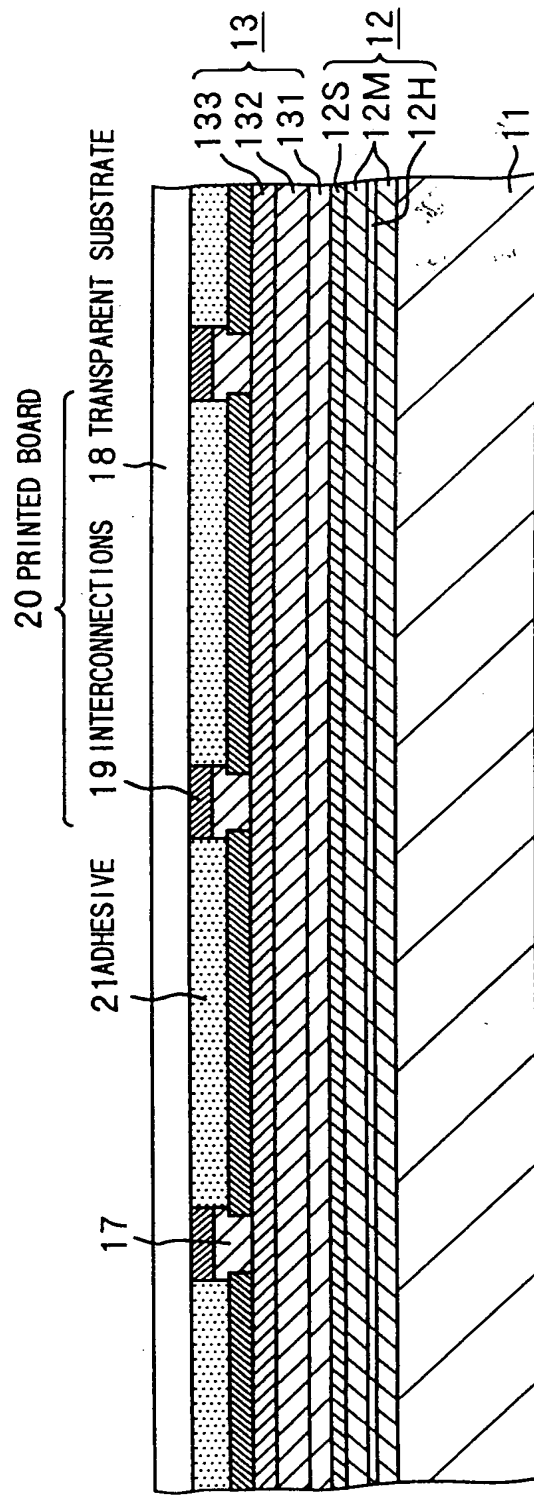


FIG.13B

PROCESS DIAGRAM (THIRD)

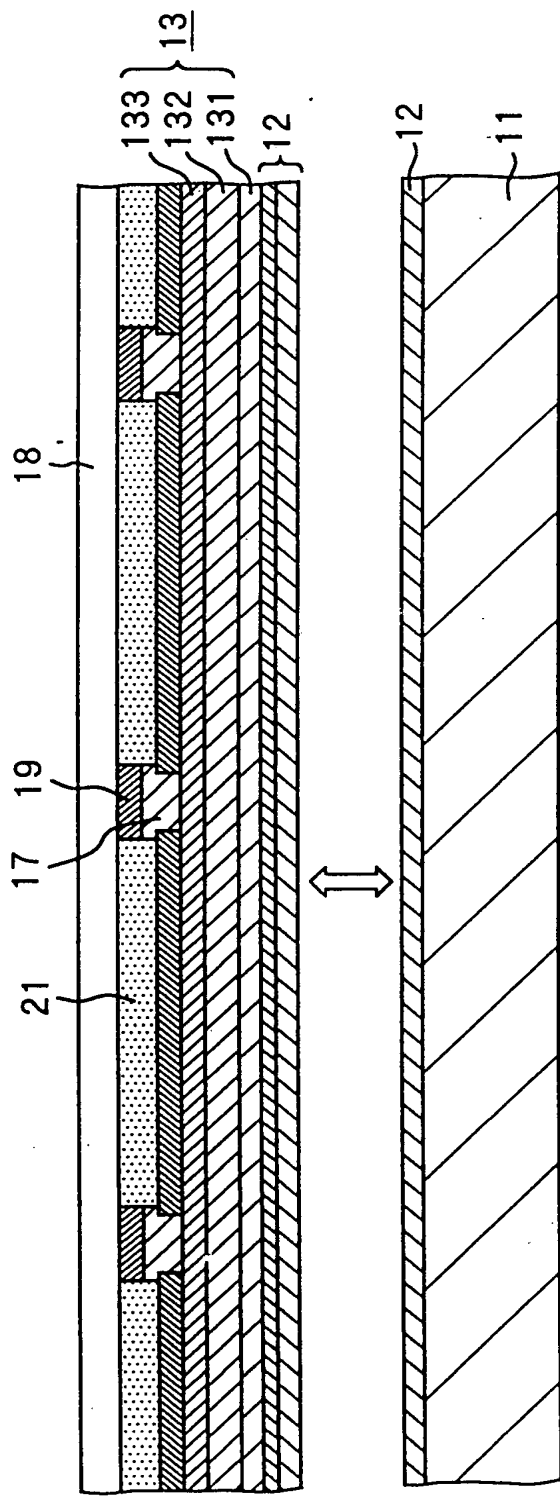


FIG.14A

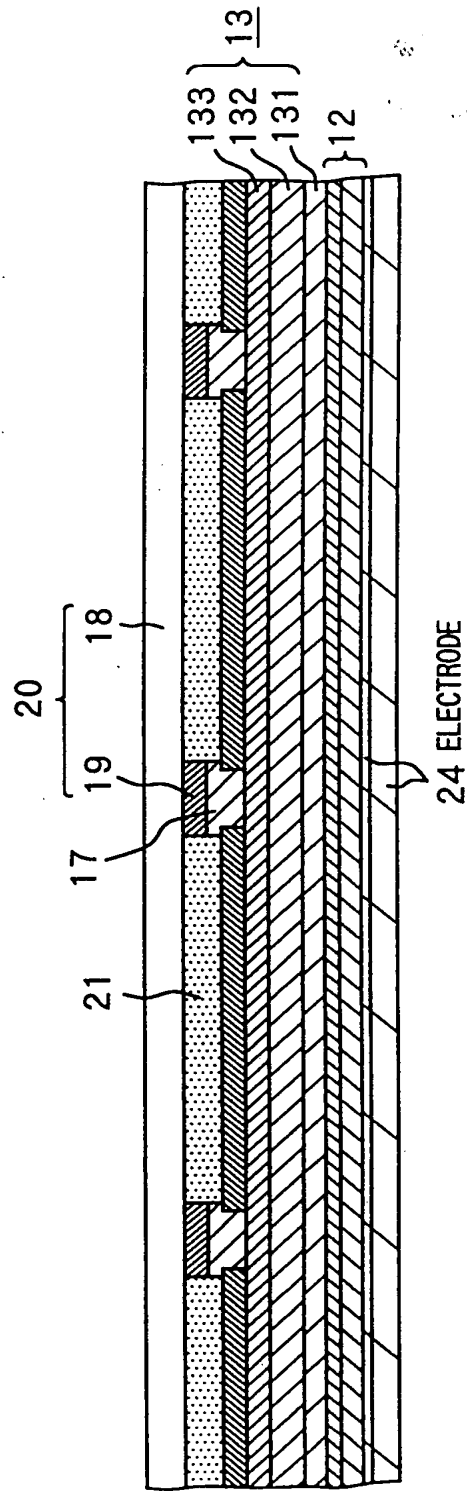


FIG.14B

PROCESS DIAGRAM (FOURTH)

FIG.15A

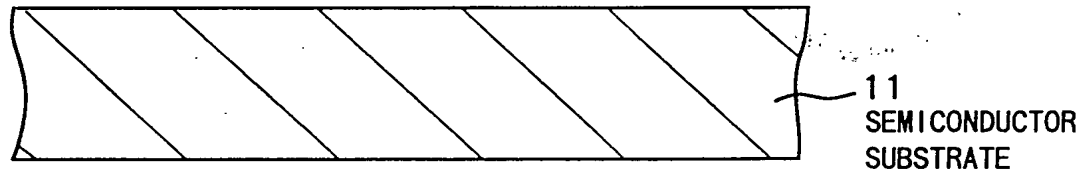


FIG.15B

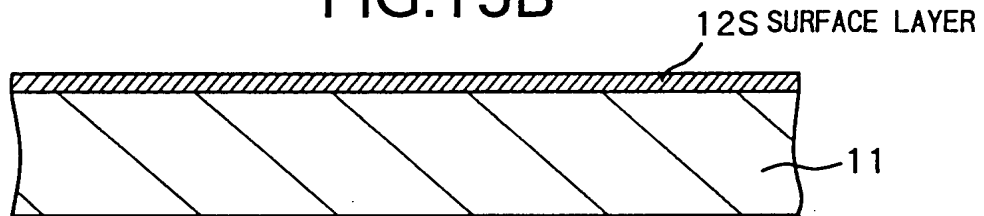


FIG.15C

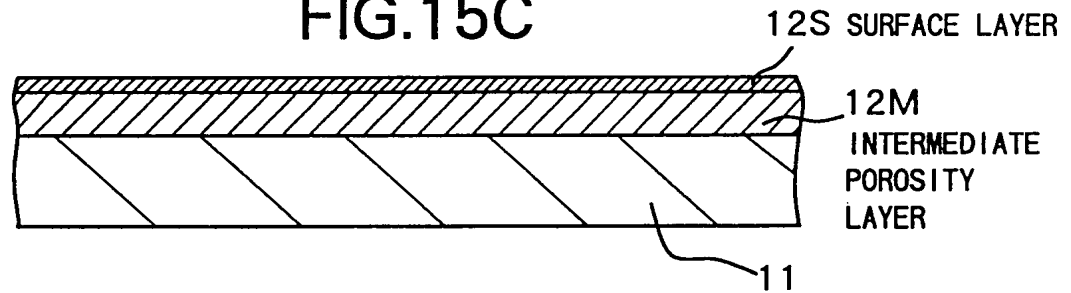
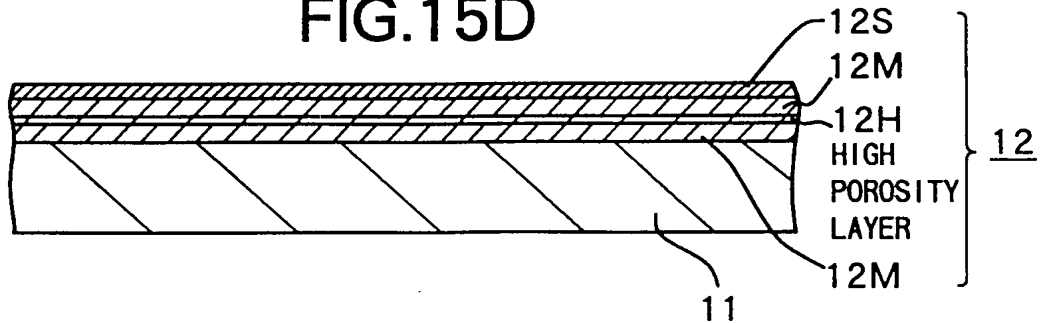


FIG.15D



PROCESS DIAGRAM(FIRST)

FIG.16A

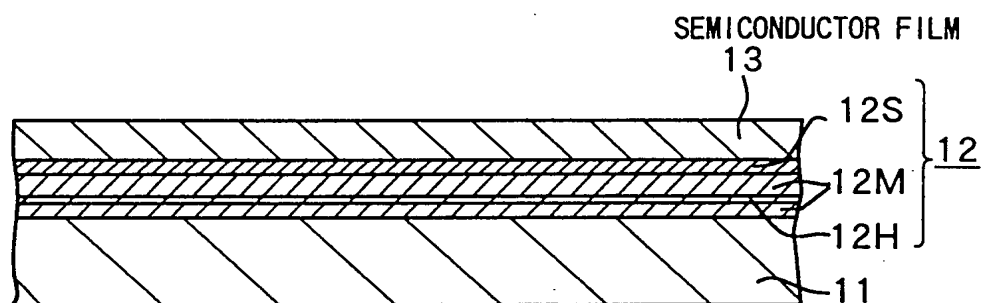
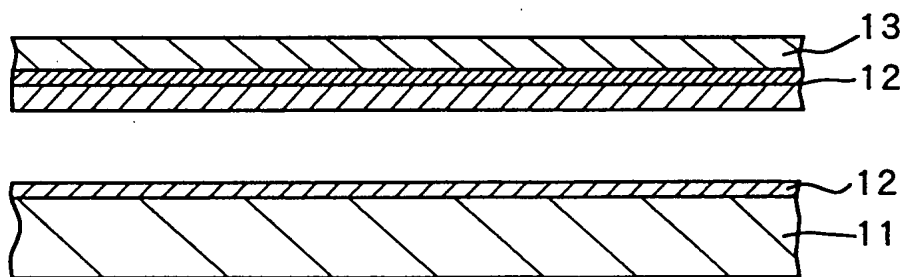


FIG.16B



PROCESS DIAGRAM (SECOND)



FIG.17A

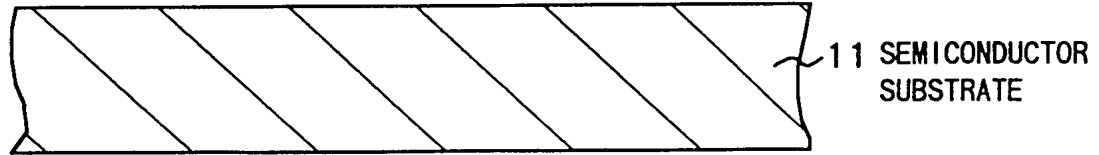


FIG.17B

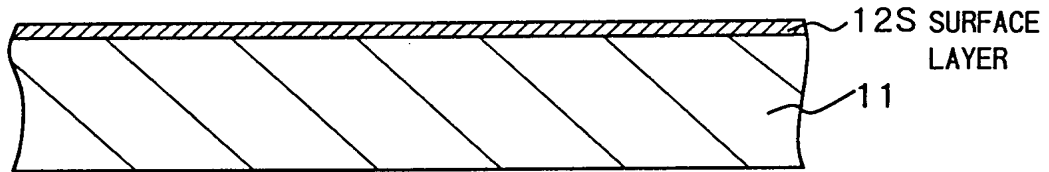


FIG.17C

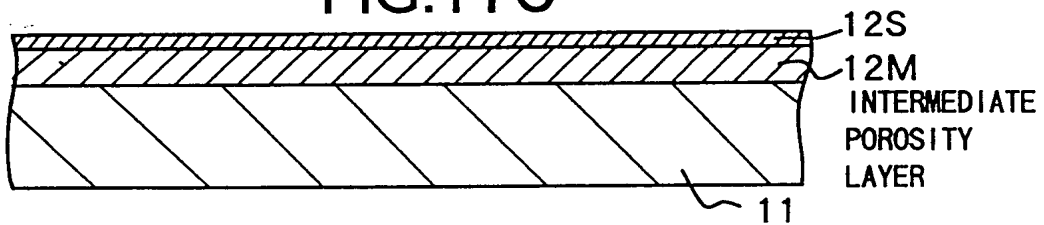


FIG.17D

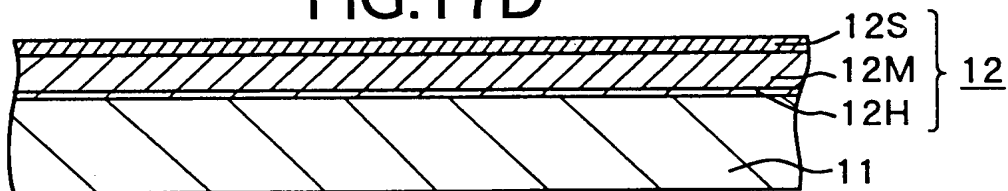
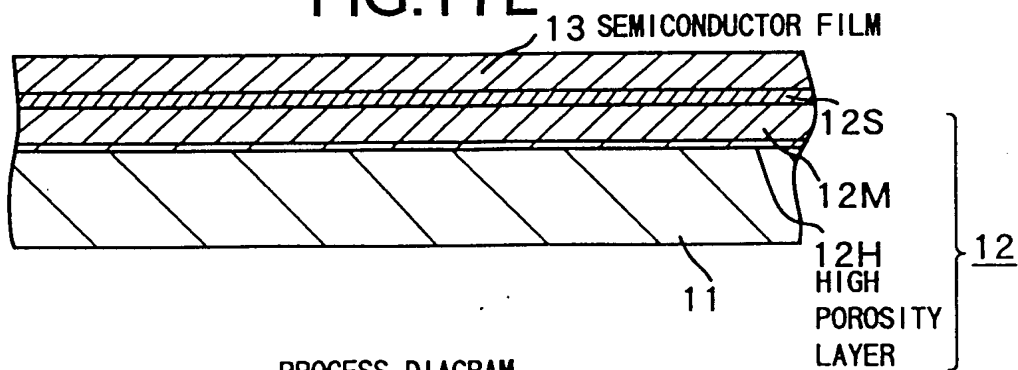


FIG.17E



PROCESS DIAGRAM

FIG.18A

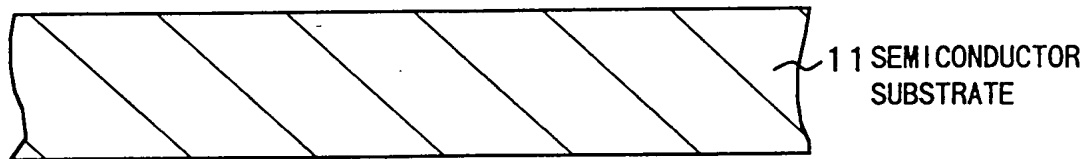


FIG.18B

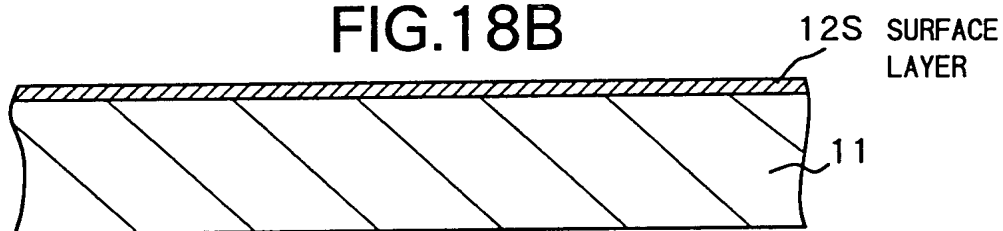


FIG.18C

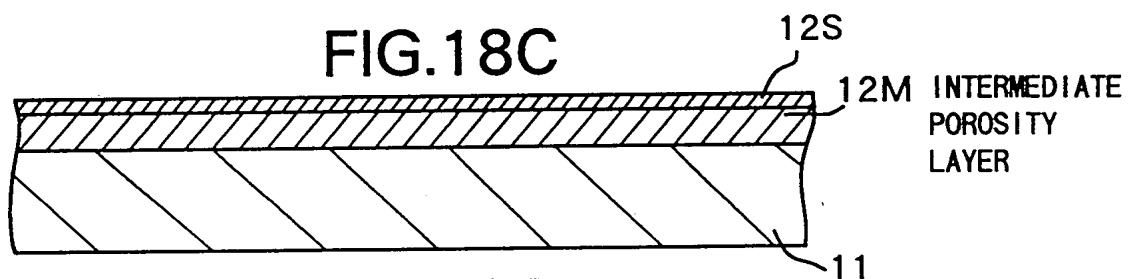


FIG.18D

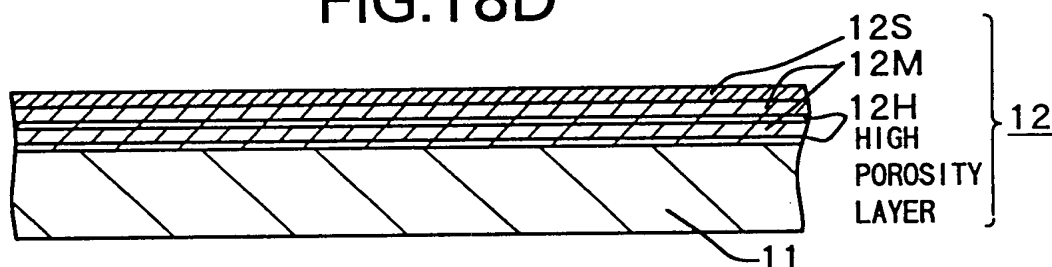
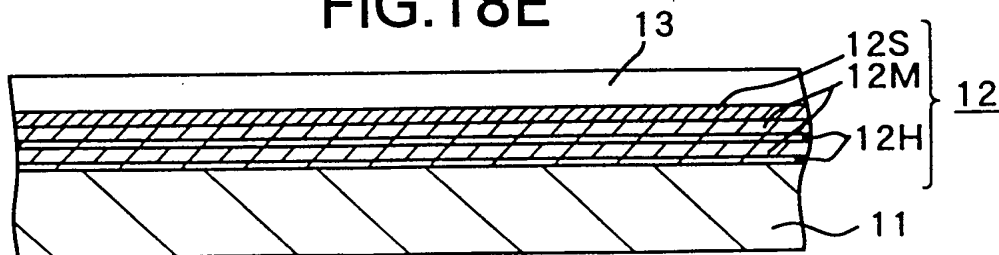


FIG.18E



PROCESS DIAGRAM

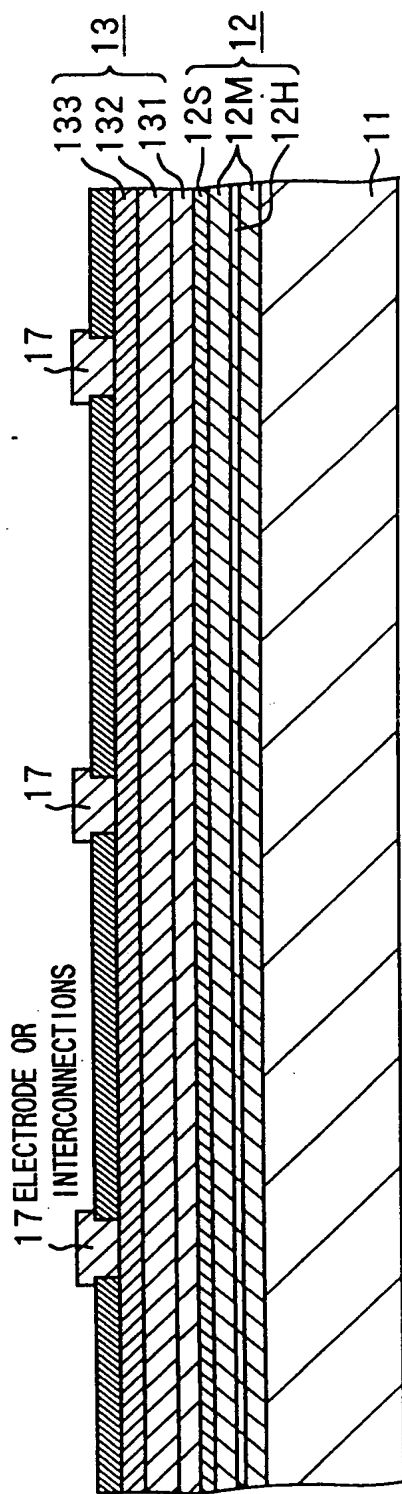


FIG.19A

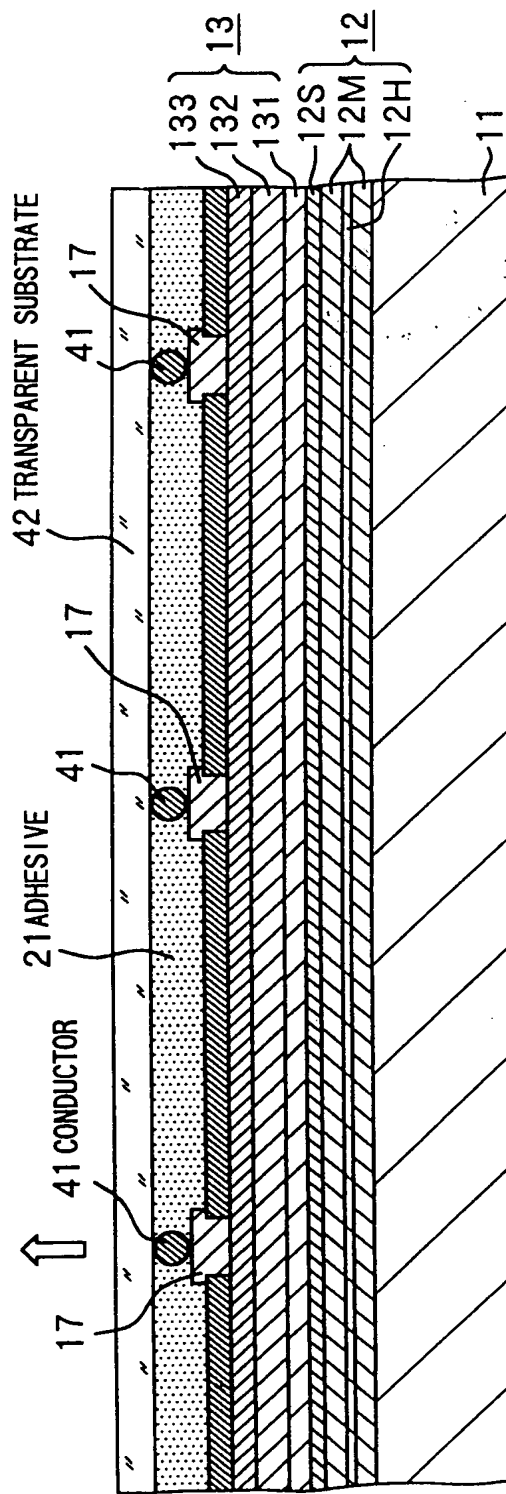


FIG.19B



PROCESS DIAGRAM(FIRST)

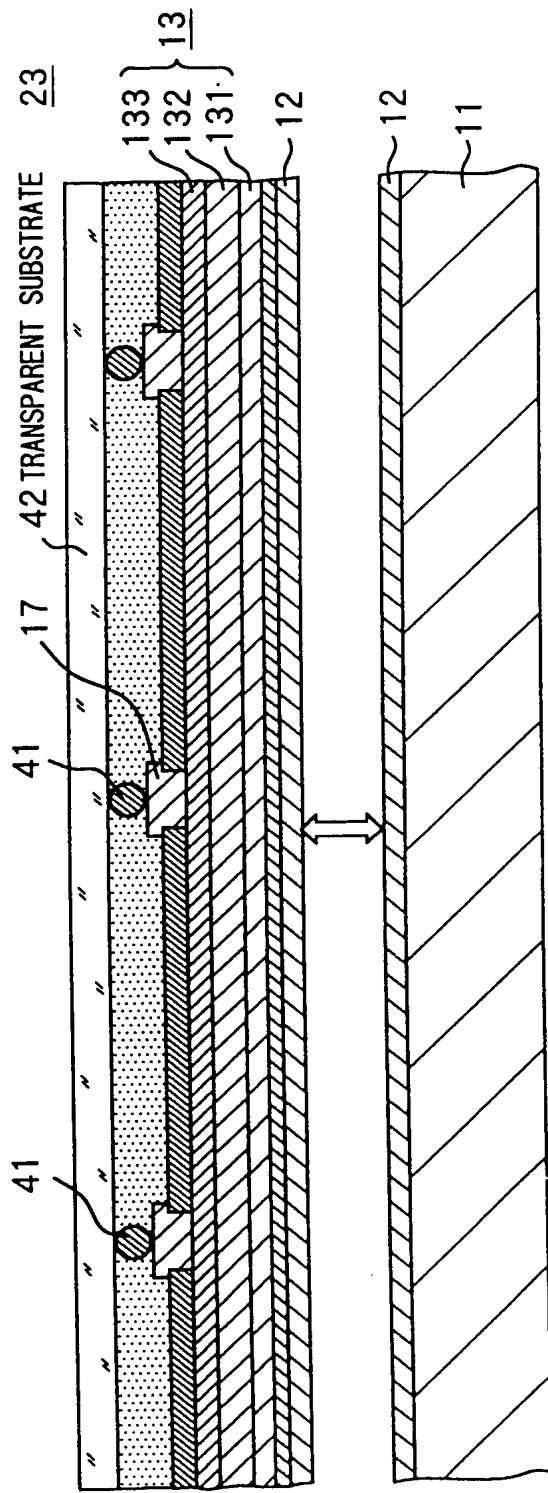


FIG. 20A

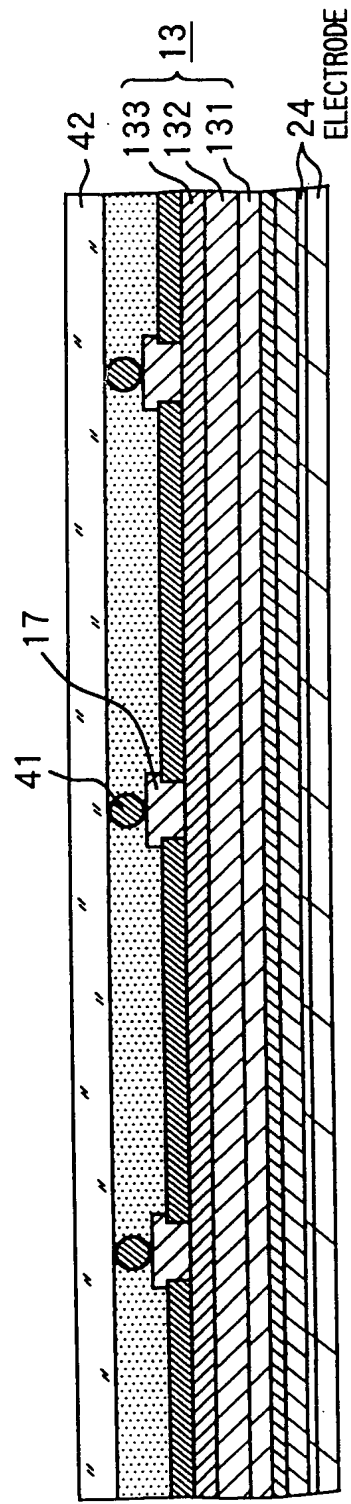


FIG. 20B

PROCESS DIAGRAM (SECOND)

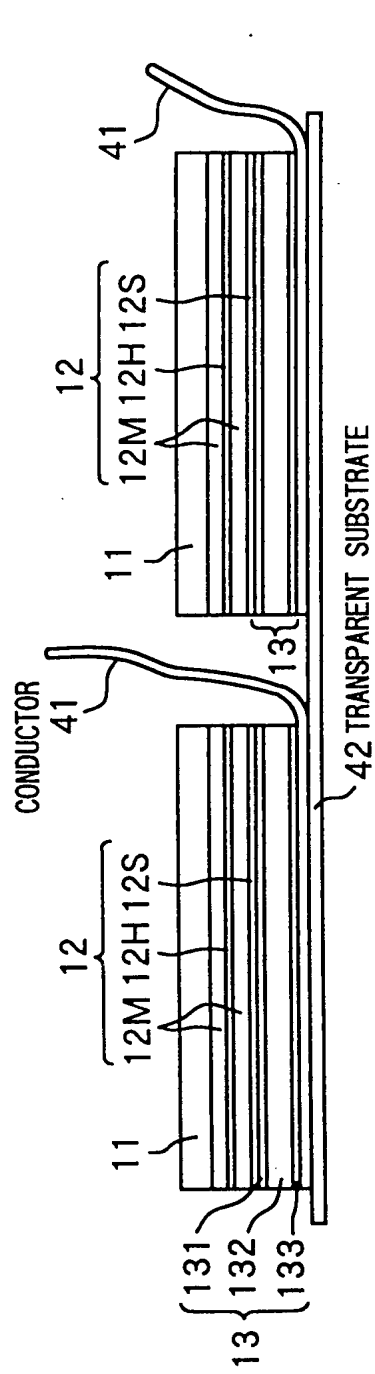


FIG. 21A

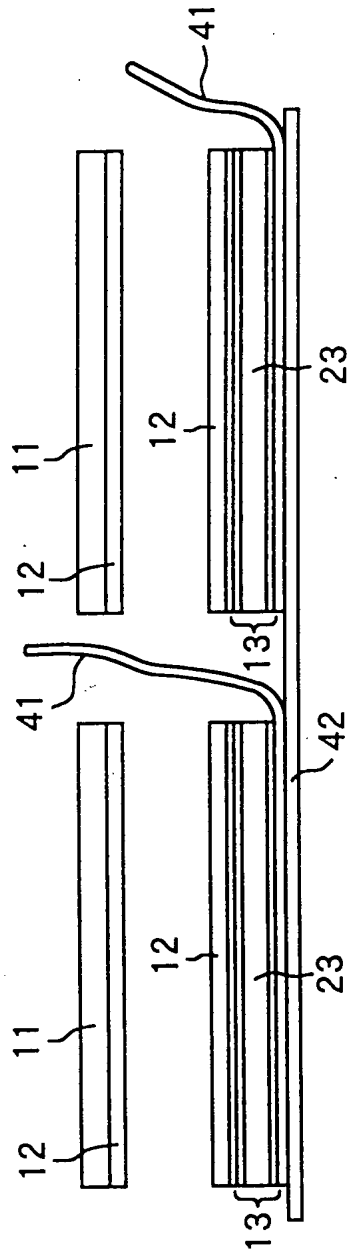


FIG. 21B

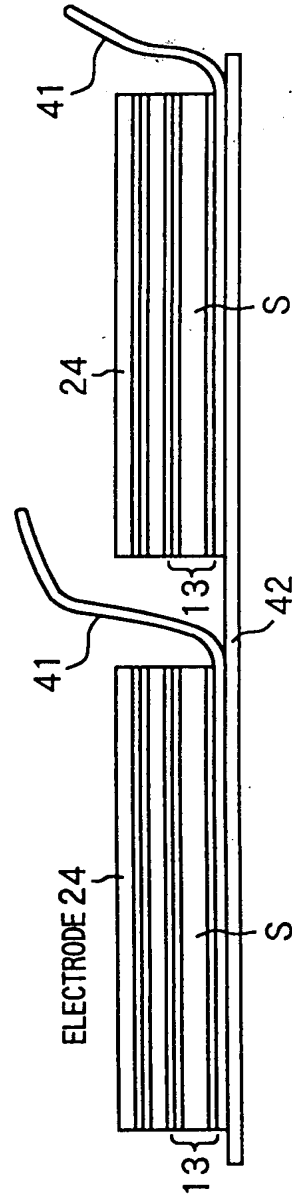


FIG. 21C

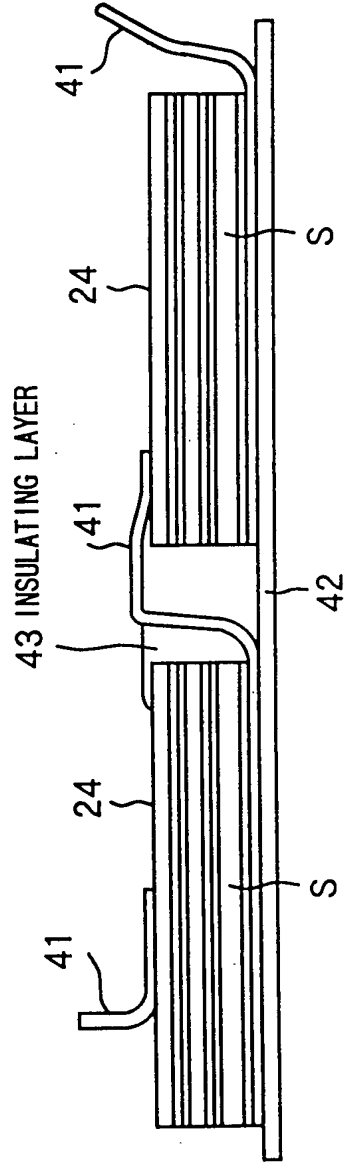


FIG. 22A

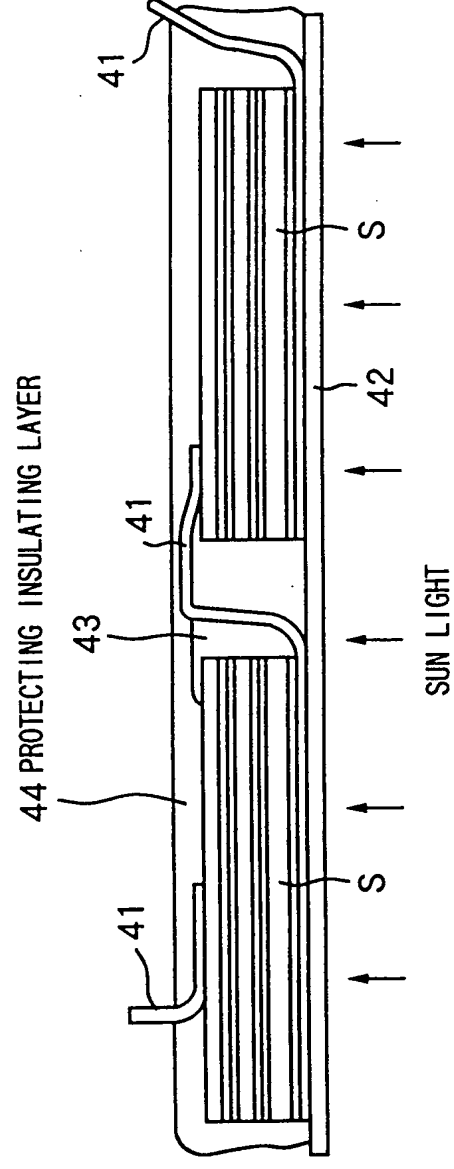


FIG. 22B

FIG.23

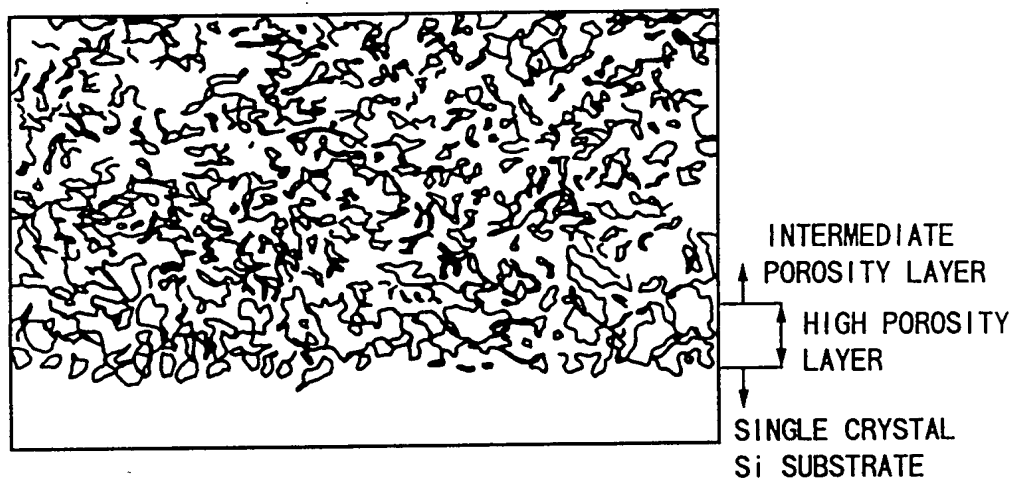
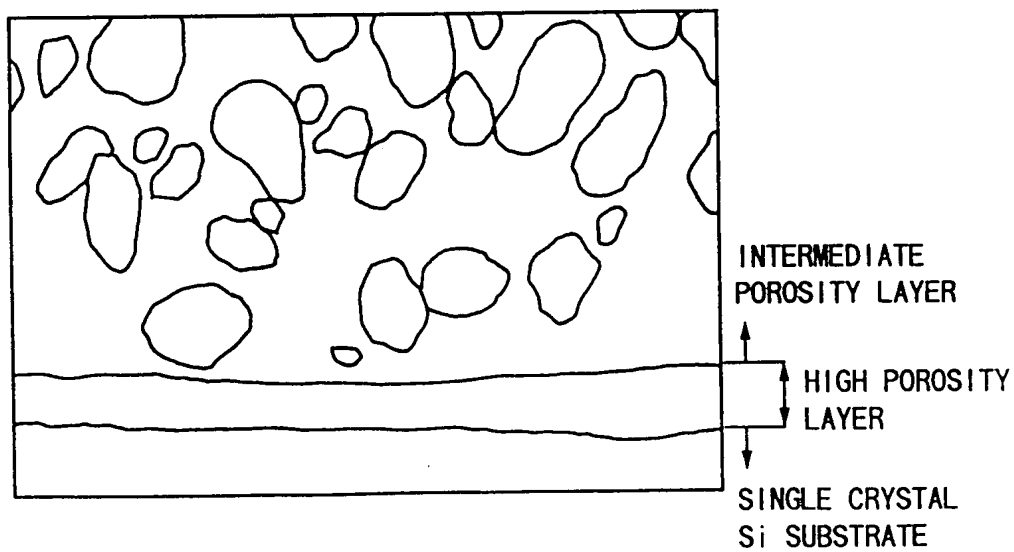
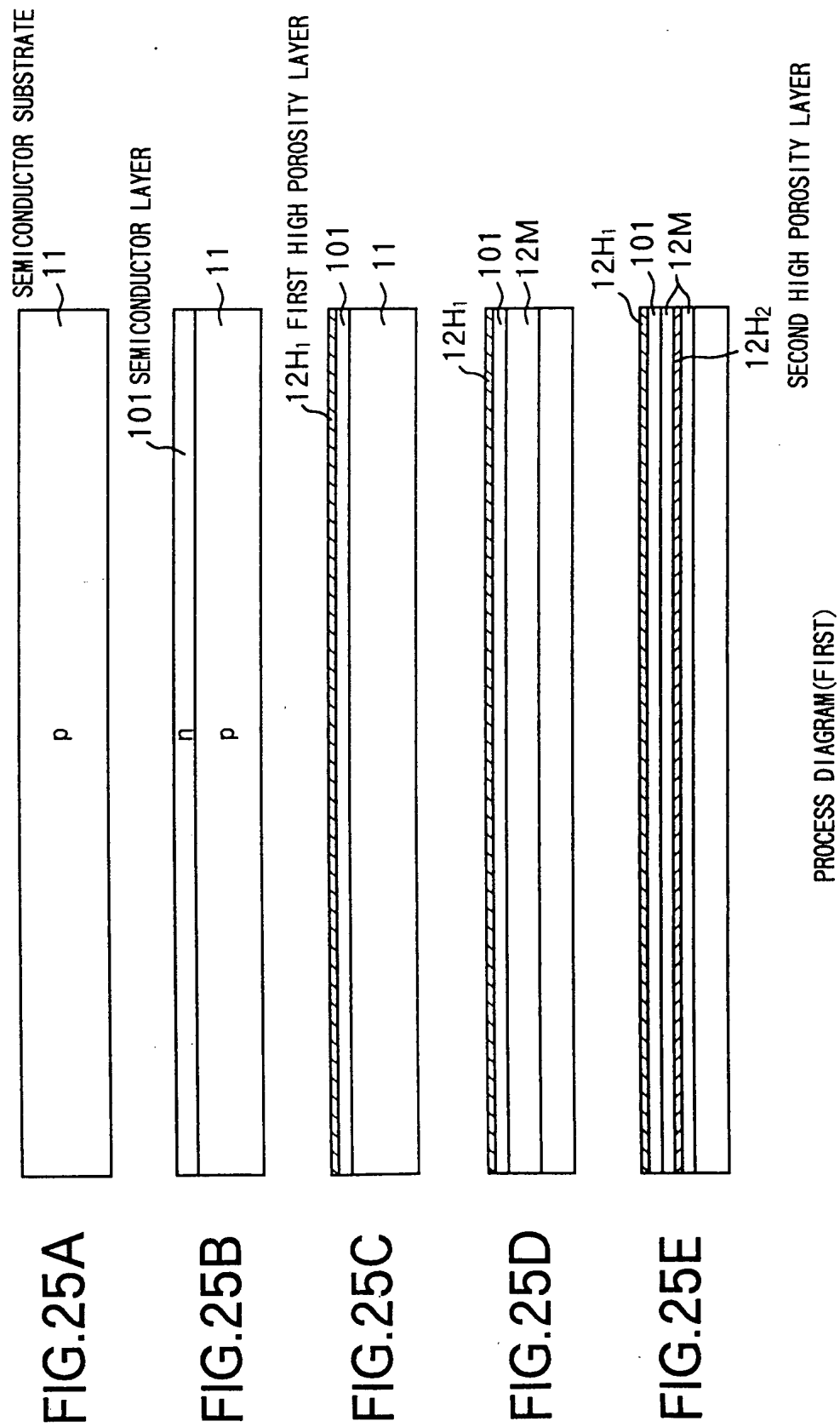


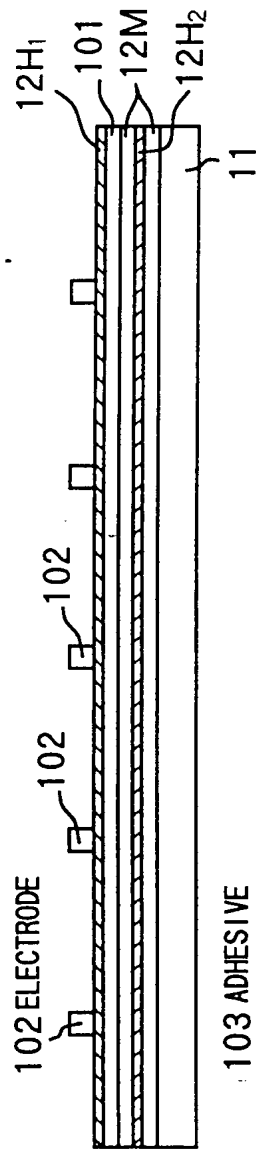
FIG.24



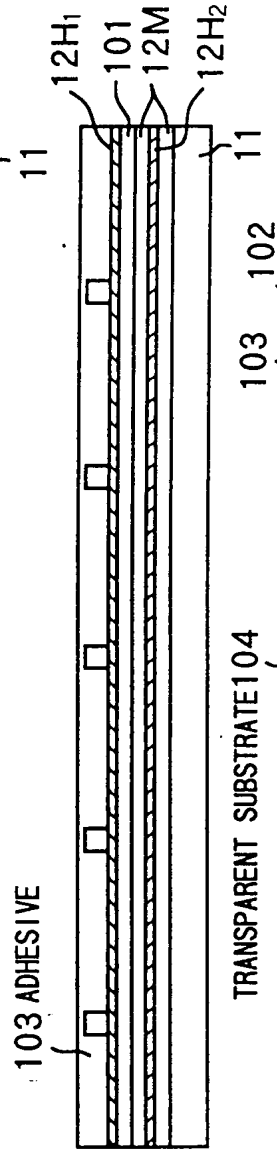




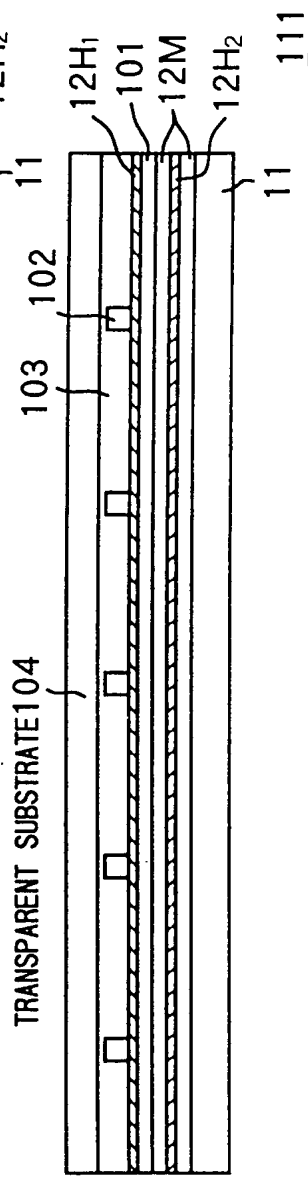
**FIG. 26A**



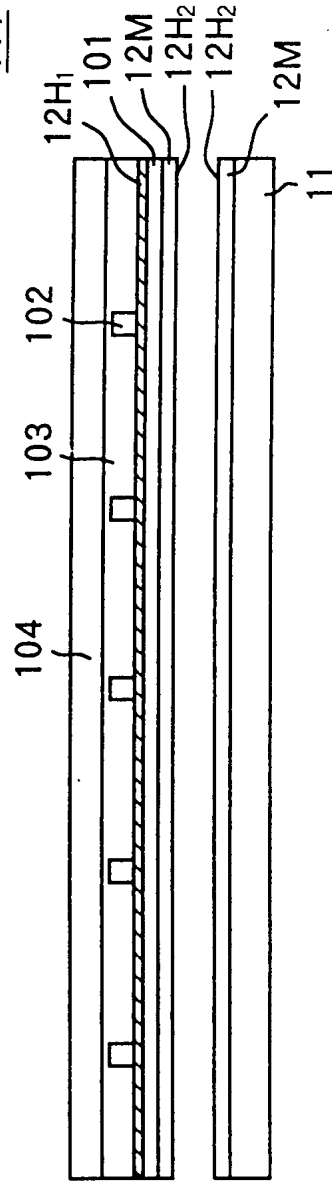
**FIG. 26B**



**FIG. 26C**



**FIG. 26D**



### PROCESS DIAGRAM (SECOND)

106  
ELECTRODE

105  
SEMICONDUCTOR LAYER

101  
SEMICONDUCTOR LAYER

102

103

104

111

A cross-sectional view of a multi-layered structure. The structure consists of several layers. From top to bottom, the layers are labeled: 101 (a thin top layer), 102 (a layer containing small square features), 103 (a layer containing larger square features), 104 (a layer containing larger square features), 105 (a thin layer), and 106 (a bottom layer containing small square features). A hatched region labeled 12H<sub>1</sub> is located between layers 101 and 102. A bracket labeled 103 ADHESIVE spans across layers 103, 104, and 105.

### PROCESS DIAGRAM(THIRD)

FIG.28A

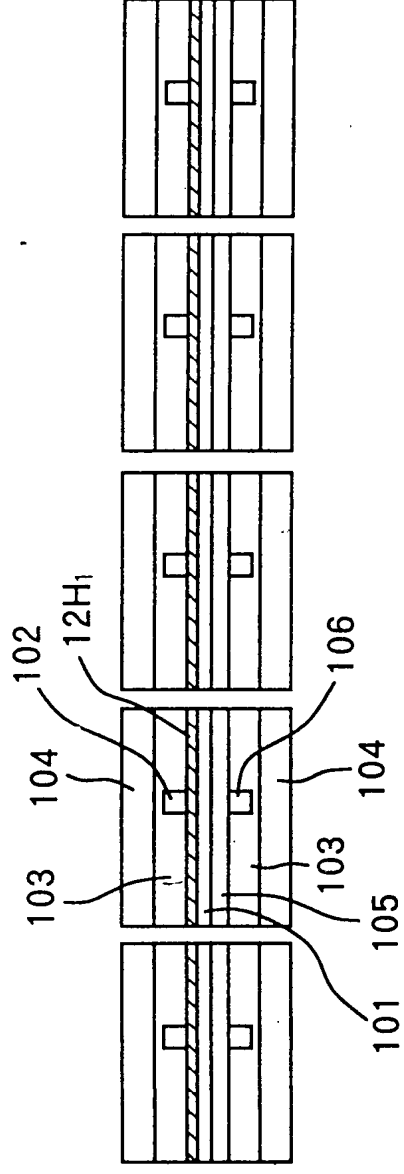
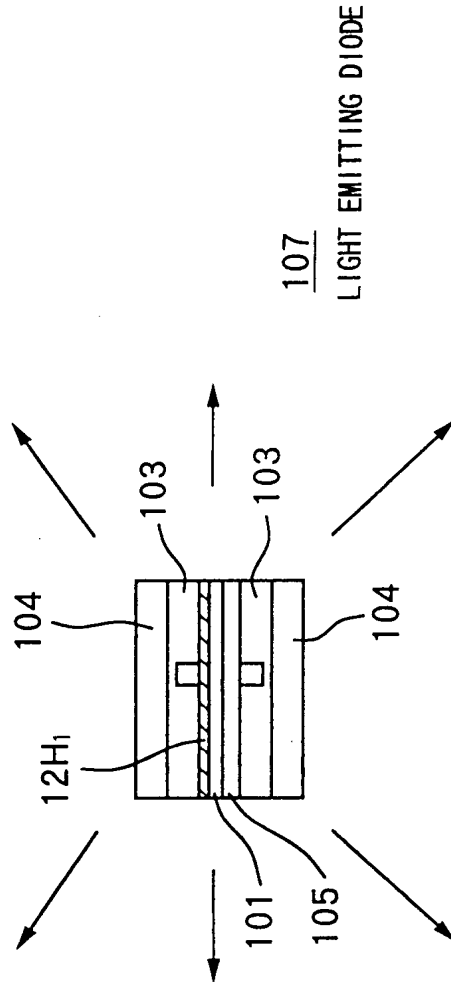


FIG.28B



PROCESS DIAGRAM (FOURTH)